



Koh Young Highlighting 3D Inspection for Advanced Packaging at SEMICON Japan 2025 in Tokyo Big Sight

Seoul, Korea – Koh Young Technology, the global leader in True 3D measurement-based inspection and metrology solutions, will showcase its latest semiconductor inspection portfolio at SEMICON Japan 2025, held from December 17 to 19 at Tokyo Big Sight in Booth E5528. This year's exhibit highlights Koh Young's commitment to delivering production-speed and high-precision inspection solutions for advanced packaging applications, including high-density substrates and mirror-like die surfaces.

Koh Young will feature two systems that expand True 3D inspection into critical semiconductor processes. The Meister D+ system will be operating in the booth for live demonstrations, and a ZenStar model will be onsite to facilitate discussion with our process experts:

- **Meister D+ Breakthrough in True 3D Measurement for Highly Reflective Components**

The Meister D+ provides a comprehensive inspection solution utilizing advanced 3D optical technology and AI-driven analysis to detect all possible defects in semiconductor back-end and advanced packaging processes. It reliably identifies and analyzes micro-cracks, chipping, foreign materials, and other critical defects that may occur in SiP manufacturing.



- **ZenStar True 3D Inspection Solutions for Advanced and Wafer-level Packaging**

The ZenStar offers a robust inspection solution capable of fully detecting all potential defects in wafer-level packaging (WLP) processes. By integrating laser optical technology with a 2D/3D multi-modal approach, it ensures stable and highly accurate detection and analysis of defects such as micro-cracks, chipping, foreign materials, solder bumps, micro-bumps, and other critical packaging defects in increasingly miniaturized applications.

“SEMICON Japan brings together the leaders driving the future of advanced packaging,” said Tom Hattori, President of Koh Young Japan. “Our Meister D+ and ZenStar solutions reflect our commitment to deliver True 3D measurement and reliable defect detection at production speeds, helping customers stabilize processes and improve yield.”



Today, Koh Young continues to address increasingly complex applications such as surface mount, machined components, press-fit and through-hole pins, conformal coating, dispensing, and semiconductor packaging. The company's ongoing innovation and customer-driven R&D remain the driving forces behind its market leadership. Koh Young uses its global network of offices and regional teams to deliver local support, training, and process expertise, helping manufacturers turn inspection data into decisive, closed-loop actions on the path to a smart factory.

Koh Young invites visitors to Booth E5528 to see live demonstrations and discuss specific advanced packaging challenges with our team of expert engineers.



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About Koh Young Technology, Inc.

Koh Young helps manufacturers prevent defects, stabilize processes, and increase throughput. Since 2002, the company has led True3D™ measurement-based metrology and inspection, beginning with the industry's first 3D solder paste inspection system using patented dual-projection Moiré technology. Building on that foundation, Koh Young addresses complex applications including surface mount assembly, through-hole, press-fit pins, conformal coatings, dispensed materials, machined parts, and semiconductor packaging. A continuous innovation mindset and a customer-focused R&D approach underpin its leadership. With global operations and regional teams, Koh Young provides local support, training, and process expertise that turn inspection data into decisive, closed-loop action for a smarter factory. Learn more about True 3D measurement-based inspection and metrology solutions at www.kohyoung.com.